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Dated: August 23, 2002

Signature: *Lawrence E. Russ*

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Docket No.: TESSERA 3.0188 DIV 9 (PATENT)

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AUG 29 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Joseph Fjelstad

Application No.: 09/785,104

Group Art Unit: 2826

Filed: February 16, 2001

Examiner: K. V. Quinto

For: MICROELECTRONIC ELEMENTS WITH
DEFORMABLE LEADS

Commissioner for Patents
Washington, DC 20231

AMENDMENT

Dear Sir:

In response to the official action mailed May 22, 2002, applicant submits the following amendments and remarks.

IN THE CLAIMS

CLEAN COPY OF AMENDED CLAIMS:

10. (Amended) A microelectronic element comprising:

(a) a body defining a front surface, said body having pads exposed at said front surface, wherein said body is a unitary semiconductor wafer including a plurality of semiconductor chips; and

(b) flexible leads having pad ends and tip ends, said pad ends of said flexible leads being connected to said pads, said tip ends of at least some of said flexible leads projecting over said front surface of said body, at least some of said flexible leads being spaced apart from said front surface, said tip ends of said flexible leads being independently movable with respect to said body, each of said at least some of said flexible leads being curved in a plane parallel to said front surface of said body;